

Cable silicon tuner Rev. 1 — 10 July 2013

Product short data sheet

1. General description

The TDA18250A is a silicon tuner designed specifically for worldwide cable and terrestrial digital Set Top Boxes (STB).

- The TDA18250A ensures a low system cost by saving external components such as:
 - Low-Noise Amplifiers
 - Surface Acoustic Wave (SAW) filters
 - RF splitter

Moreover, thanks to its 8 kV ESD capability, EIA/JESD22-A114 (HBM), on the RF input pin and the loop-through pin, the application level ESD protection can be reduced.

- The TDA18250A silicon tuner meets current and future digital cable and terrestrial TV reception with:
 - Low-power consumption
 - High linearity
 - Very low noise figure (3.8 dB typical)
 - High immunity to wireless interferers (WLAN, LTE and GSM)
- The TDA18250A ensures ease of use with:
 - Easy on-board integration
 - Efficient and effective PCB design
 - Reduced external components
 - Integrated Zero Power Loop-Through (ZPLT)

2. Features and benefits

- Single 3.3 V supply voltage
- RF frequency coverage up to 1 GHz
- Flexible low IF output from 3 MHz to 7.5 MHz to ease the matching with various demodulators
- RoHS compliant
- I²C-bus interface compatible with 3.3 V microcontrollers
- Strong Immunity to wireless interferers (WLAN, GSM, LTE)
- Multi-reference clock frequency compliant:16 MHz, 24 MHz, 25 MHz, 27 MHz and 30 MHz
- Crystal oscillator output buffer to drive demodulator, SoC or slave tuner
- Slave Tuner Output (STO), integrated splitter for dual tuner applications



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- Fully integrated oscillators
- LT output, both in active and Zero Power Loop-Through mode (ZPLT)
- Fully integrated IF and RF selectivity; eliminating the need for external SAW filters
- Single-ended RF input (no need for external balun)
- Enhanced ESD protection (8 kV HBM) on RF_IN and ZPLT pins
- Alignment free
- Excellent return loss compatible with cable requirements
- Integrated RSSI function, readable through I²C-bus
- Integrated temperature sensor
- Integrated gain control

3. Quick reference data

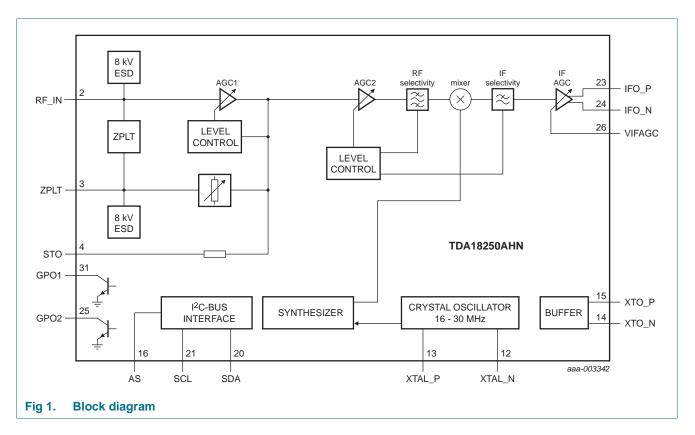
Table 1.	Quick reference data					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f _{RF}	RF frequency	RF input frequency range	42	-	1002	MHz
NF _{tun}	tuner noise figure	75 Ω; maximum gain				
		f _{RF} < 862 MHz	-	3.8	-	dB
		$f_{RF} \geq 862 \ MHz$	-	4.5	-	dB
Φjit	phase jitter	integrated from 250 Hz to 4 MHz	-	0.4	0.6	Degree
α_{image}	image rejection	$\begin{array}{l} \text{IF} = 5 \text{ MHz, RF (image)} \\ \text{Ievel} \geq 60 \text{ dB} \mu \text{V} \end{array}$	-	62	-	dB
P _{i(max)}	maximum input power	single channel	115	-	-	dBμV
Ρ	power dissipation		-	0.740	-	W

4. Ordering information

Table 2. Ordering information					
Type number	Package	age			
	Name	Description	Version		
TDA18250AHN/C1	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body $5 \times 5 \times 0.85$ mm	SOT617-3		

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5. Block diagram



6. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.3	+3.60	V
V _I input voltage	input voltage	V _{CC} < 3.3 V	-0.3	$V_{CC} + 0.3$	V
		V _{CC} > 3.3 V	-0.3	+3.6	V
V _{ESD}	electrostatic discharge voltage	EIA/JESD22-A114 (HBM)	2	-	kV
		EIA/JESD22-A114 (HBM); pins RF_IN and ZPLT	8	-	kV
		EIA/JESD22-C101-C (FCDM)	<u>[1]</u> 1	-	kV

[1] It withstands class IV of JEDEC standard.

TDA18250AHN_SDS
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7. Abbreviations

AcronymDescriptionAGCAutomatic Gain ControlESDElectroStatic DischargeFCDMField Charge Device ModelGPOGeneral Purpose OutputsHBMHuman Body ModelICIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughCRRadio FrequencyPCBPrinted-Circuit BoardRFRadio FrequencyRSIRestriction of Hazardous SubstancesRSSISerial CLockSQLSerial CLockSDASerial CLockSTBSet Top BoxSTGSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystalZPLTZero Power Loop-Trough	Table 4.	Abbreviations
ESDElectroStatic DischargeESDElectroStatic DischargeFCDMField Charge Device ModelGPOGeneral Purpose OutputsHBMHuman Body ModelICIntegrated CircuitIFIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputVLANWireless Local Area NetworkXtalCrystal	Acronym	Description
FCDMField Charge Device ModelGPOGeneral Purpose OutputsHBMHuman Body ModelICIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyROHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	AGC	Automatic Gain Control
GPOGeneral Purpose OutputsHBMHuman Body ModelICIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	ESD	ElectroStatic Discharge
HBMHuman Body ModelICIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	FCDM	Field Charge Device Model
ICIntegrated CircuitIFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSOCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	GPO	General Purpose Outputs
IFIntermediate FrequencyJEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	HBM	Human Body Model
JEDECJoint Electron Device Engineering CouncilLTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	IC	Integrated Circuit
LTLoop-ThroughLTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	IF	Intermediate Frequency
LTELong-Term EvolutionPCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	JEDEC	Joint Electron Device Engineering Council
PCBPrinted-Circuit BoardRFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	LT	Loop-Through
RFRadio FrequencyRoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	LTE	Long-Term Evolution
RoHSRestriction of Hazardous SubstancesRSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	PCB	Printed-Circuit Board
RSSIReceived Signal Strength IndicatorSAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	RF	Radio Frequency
SAWSurface Acoustic WaveSCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	RoHS	Restriction of Hazardous Substances
SCLSerial CLockSDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	RSSI	Received Signal Strength Indicator
SDASerial DAtaSoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	SAW	Surface Acoustic Wave
SoCSystem on ChipSTBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	SCL	Serial CLock
STBSet Top BoxSTOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	SDA	Serial DAta
STOSlave Tuner OutputWLANWireless Local Area NetworkXtalCrystal	SoC	System on Chip
WLAN Wireless Local Area Network Xtal Crystal	STB	Set Top Box
Xtal Crystal	STO	Slave Tuner Output
	WLAN	Wireless Local Area Network
ZPLT Zero Power Loop-Trough	Xtal	Crystal
	ZPLT	Zero Power Loop-Trough

8. Revision history

Table 5. Revision histo	Revision history				
Document ID	Release date	Data sheet status	Change notice	Supersedes	
TDA18250AHN_SDS v.1	20130710	Product short data sheet	-	-	

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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